ADVANCED PACKAGING

Discover our capabilities

C2MI offers a wide range of equipment to conduct the advanced packaging of semiconductors as a finished product on a substrate ready for assembly to the card.

C2MI's facilities allow thinning and dicing of 200mm and 300mm wafers, flip chip or wire bonding with positioning accuracy of up to 1 µm for all types of integrated circuit components or optoelectronics.

Our processes

- Dicing
- Picking
- Chip joining
- Underfill
- Die attach
- Wire bond
- Caping
- Balling
- Marking

The Centre

C2MI is the largest research and development centre in microelectronic across Canada. Offering state-of-the-art equipment dedicated mainly to advanced packaging and micro-electromechanical systems (MEMS), the Centre also welcomes together more than 250 scientists in research and development (R & D).

« Collaboration and synergy among our partners promote rapid commercialization of advanced prototypes. »

MiQro Innovation
Collaborative Centre

45 boulevard de l’Aéroport
Bromont, QC, Canada, J2L 1S8
450-534-8000
www.c2mi.ca